TI No. TI-35917 1 of 9 Inventor: Grunow et al.

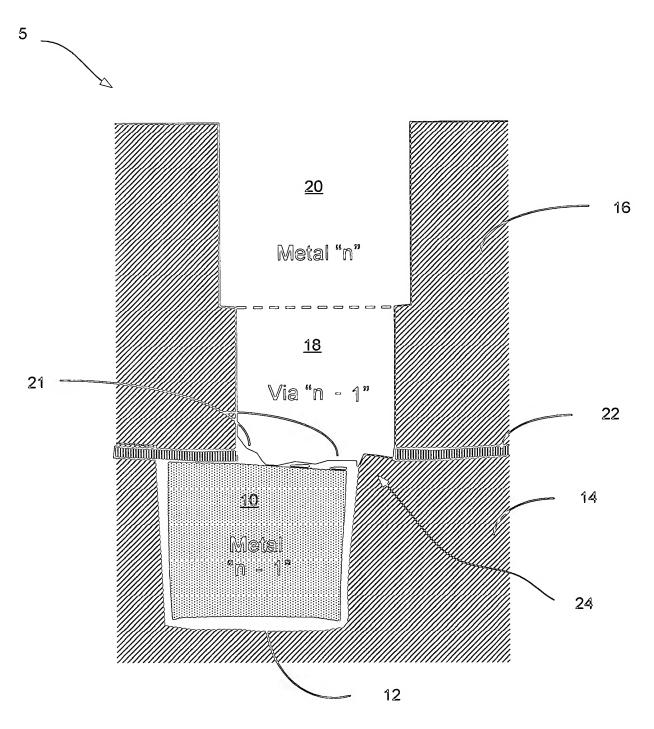


Fig. 1A

TI No. TI-35917 2 of 9 Inventor: Grunow et al.

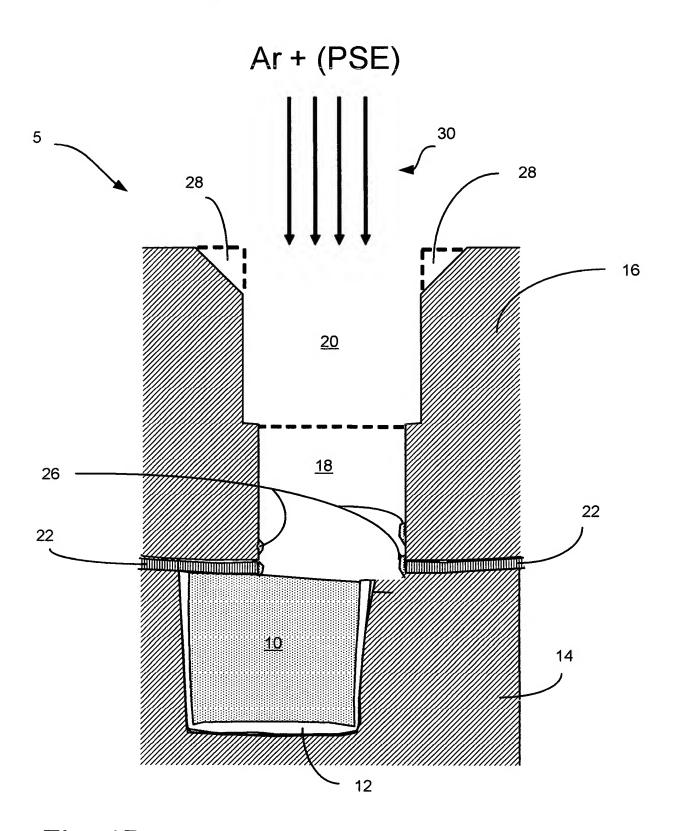


Fig. 1B

TI No. TI-35917 3 of 9 Inventor: Grunow et al.

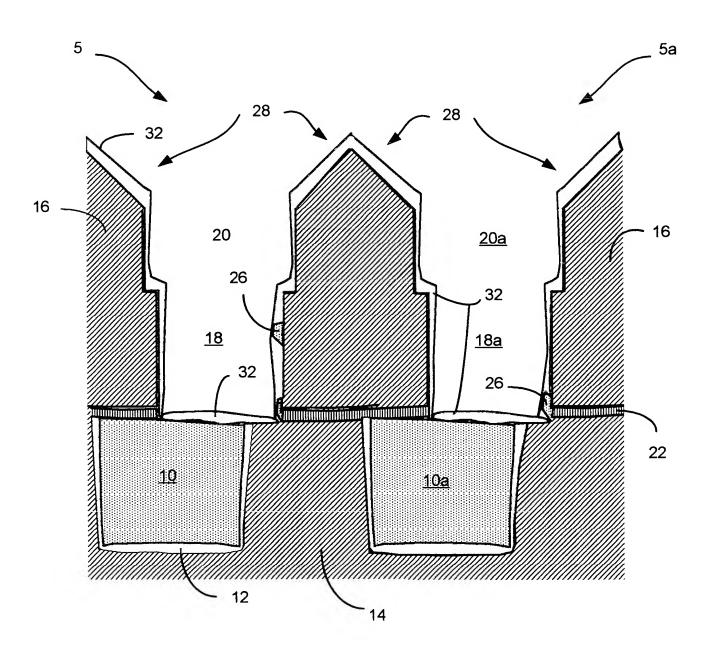


Fig. 1C

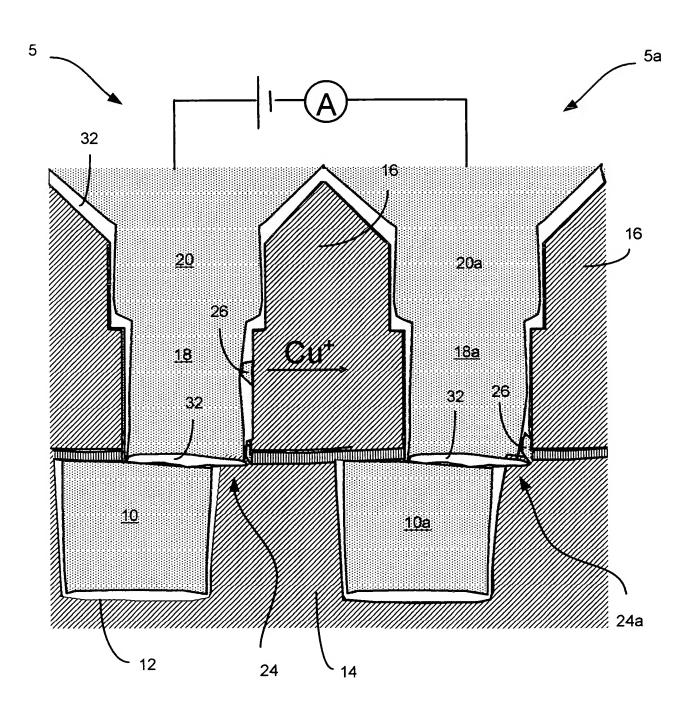


Fig. 1D

TI No. TI-35917 5 of 9 Inventor: Grunow et al.

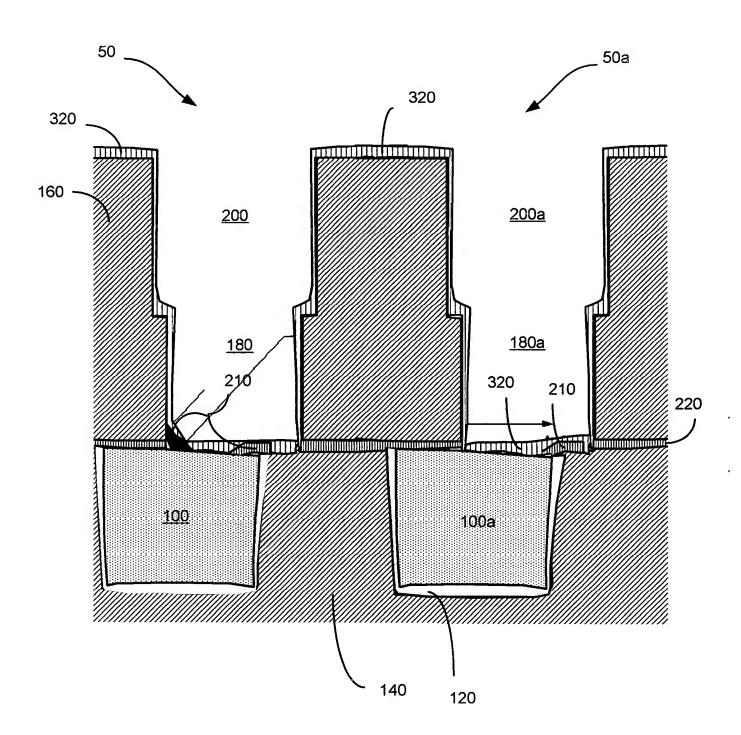


Fig. 2A

TI No. TI-35917 6 of 9 Inventor: Grunow et al.

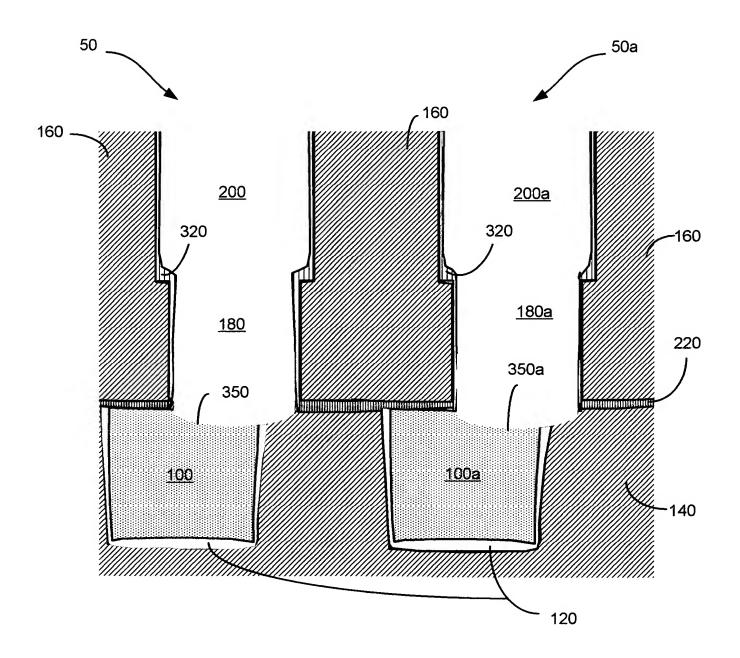


Fig. 2B

Ti No. Ti-35917 7 of 9 Inventor: Grunow et al.

Title: A Stacked Interconnect Structure between

Copper Lines of a Semiconductor Circuit

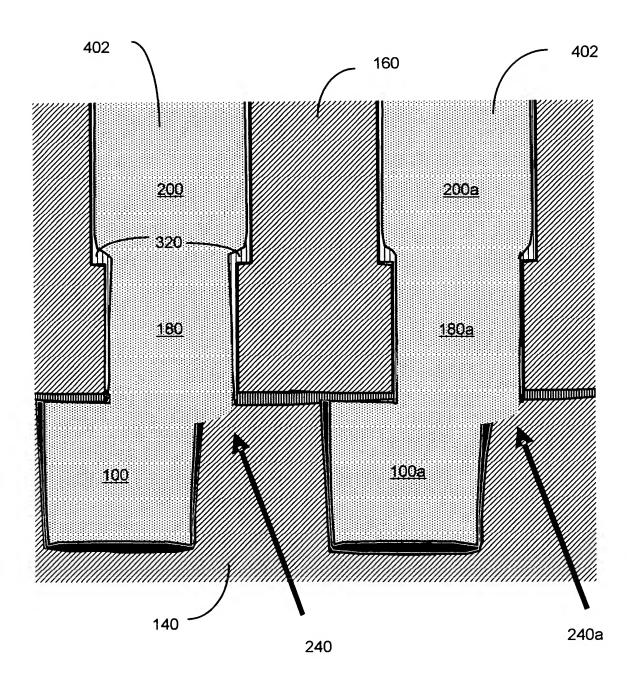


Fig. 2C

TI No. TI-35917 8 of 9 Inventor: Grunow et al.

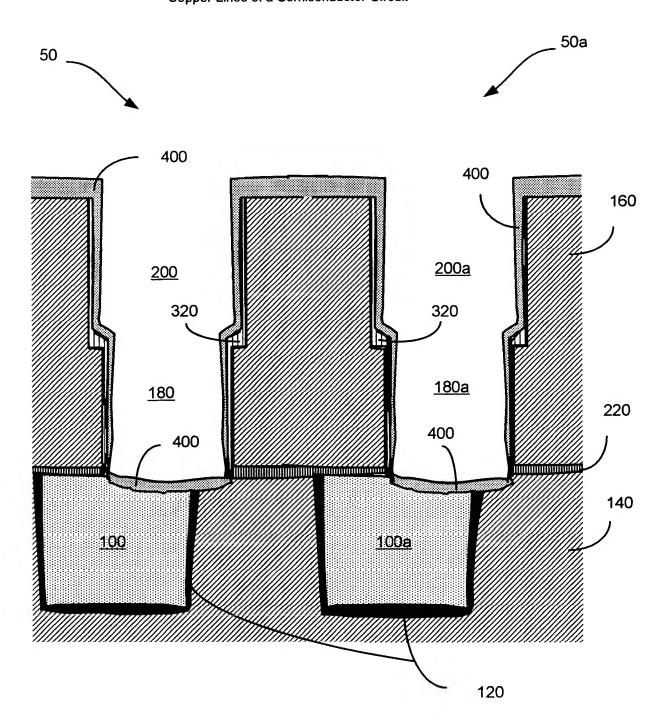


Fig. 2D

Ti No. Ti-35917 9 of 9 Inventor: Grunow et al.

Title: A Stacked Interconnect Structure between

Copper Lines of a Semiconductor Circuit

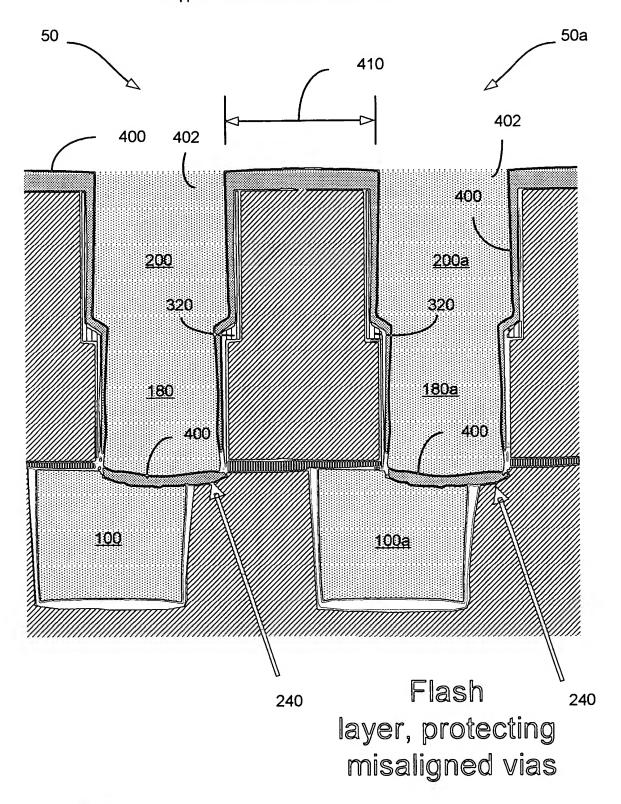


Fig. 2E